

STN	Skúšobné metódy pre elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy. Časť 2-721: Skúšobné metódy pre materiály na spájacie štruktúry. Meranie relatívnej permitivity a činiteľa dielektrických strát medzi plátovaného laminátu pri mikrovlnnej frekvencii dielektrického rezonátora.	STN EN 61189-2-721 34 6513
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Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-721: Test methods for materials for interconnection structures - Measurement of relative permittivity and loss tangent for copper clad laminate at microwave frequency using split post dielectric resonator

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/15

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English Version

Test methods for electrical materials, printed boards and other
interconnection structures and assemblies - Part 2-721: Test
methods for materials for interconnection structures -
Measurement of relative permittivity and loss tangent for copper
clad laminate at microwave frequency using split post dielectric
resonator
(IEC 61189-2-721:2015)

Méthodes d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 2-721: Méthodes d'essai des matériaux
pour structures d'interconnexion - Mesure de la permittivité
relative et de la tangente de perte pour les stratifiés
recouverts de cuivre en hyperfréquences à l'aide d'un
résonateur diélectrique en anneaux fendus
(IEC 61189-2-721:2015)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen - Teil 2-
721: Prüfverfahren für Verbindungsstrukturen (Leiterplatten)
- Messung der relativen Permittivität und des Verlustfaktors
von kupferkaschiertem Laminat im Mikrowellen-
Frequenzbereich unter Verwendung eines Split Post
dielektrischen Resonators
(IEC 61189-2-721:2015)

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The text of document 91/1246/FDIS, future edition 1 of IEC 61189-2-721, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-2-721:2015.

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



Test methods for electrical materials, printed boards and other interconnection structures and assemblies –

Part 2-721: Test methods for materials for interconnection structures –

Measurement of relative permittivity and loss tangent for copper clad laminate at microwave frequency using split post dielectric resonator

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –

Partie 2-721: Méthodes d'essai des matériaux pour structures d'interconnexion –

Mesure de la permittivité relative et de la tangente de perte pour les stratifiés recouverts de cuivre en hyperfréquences à l'aide d'un résonateur diélectrique en anneaux fendus



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NORME INTERNATIONALE



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Part 2-721: Test methods for materials for interconnection structures –

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-721: Test methods for materials for interconnection structures –
Measurement of relative permittivity and loss tangent for copper clad
laminate at microwave frequency using split post dielectric resonator**

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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-721: Test methods for materials for interconnection structures – Measurement of relative permittivity and loss tangent for copper clad laminate at microwave frequency using split post dielectric resonator

1 Scope

This part of IEC 61189 outlines a way to determine the relative permittivity (ϵ_r) and loss tangent ($\tan\delta$) (also called dielectric constant (Dk) and dissipation factor (Df)) of copper clad laminates at microwave frequencies (from 1,1 GHz to 20 GHz) using a split post dielectric resonator (SPDR).

This part of IEC 61189 is applicable to copper clad laminates and dielectric base materials.

koniec náhľadu – text ďalej pokračuje v platenej verzii STN